


Full Material Declaration for attached parts list

Report generated: 15 June 2016, 09:56 GMT

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|  | <p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p> |
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Declaration effective from: 1 January 2009 [Approved on 15 June 2016, 09:52 GMT]

Materials and substances

| Use/Location | Material group | % w/w of material in the part | Substances in the material | CAS Number | % w/w of substance in the material |
|---------------|---|-------------------------------|----------------------------|------------|------------------------------------|
| Chip (die) | Other inorganic materials | 0.06000% | Nickel | 7440-02-0 | 1.00000% |
| | | | Gold | 7440-57-5 | 11.50000% |
| | | | Dow corning 3110 | 63394-02-5 | 25.00000% |
| | | | Silicon | 7440-21-3 | 62.50000% |
| Die attach | Sn-Pb solder | 0.03000% | Silver | 7440-22-4 | 2.50000% |
| | | | Tin | 7440-31-5 | 5.00000% |
| | | | Lead | 7439-92-1 | 92.50000% |
| Encapsulation | EP (Epoxy resin) | 41.58000% | Carbon black | 1333-86-4 | 0.30000% |
| | | | ANTIMONY TRIOXIDE | 1309-64-4 | 0.80000% |
| | | | Tetrabromobisphenol A | 79-94-7 | 0.99000% |
| | | | Epoxy resin 89 | 26335-32-0 | 27.61000% |
| | | | Quartz sand | 60676-86-0 | 70.30000% |
| Leadfinish | Tin plating | 0.48000% | Tin | 7440-31-5 | 100.00000% |
| Leadframe | Copper (e.g. copper amounts in cable harnesses) | 57.85000% | Copper | 7440-50-8 | 100.00000% |

Attached parts list

| Part number | Part name | Part Mass | Part Mass UoM |
|-------------|------------------------|-----------|---------------|
| TO-220AB/AC | Diode/Transistor Power | 1.8 | g |